

Electronic Patent Application Fee Transmittal

Application Number:	10540992			
Filing Date:	05-Jun-2006			
Title of Invention:	Chemical-mechanical-polishing slurry composition, method for planarizing surface of semiconductor device using the same, and method for controlling selection ratio of slurry composition			
First Named Inventor/Applicant Name:	Jea Gun Park			
Filer:	Robert Charles Friedt Perez/Febes lazo			
Attorney Docket Number:	061063-0316598			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				810